

<b>PATENT ASSIGNMENT COVER SHEET</b>
--------------------------------------

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT8341562

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
RAJESH KATKAR	08/16/2018
LIANG WANG	08/30/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	INVENSAS BONDING TECHNOLOGIES, INC.
<b>Street Address:</b>	3025 ORCHARD PARKWAY
<b>City:</b>	SAN JOSE
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95134
<b>PROPERTY NUMBERS Total: 3</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	18545120
<b>Application Number:</b>	18545136
<b>Application Number:</b>	17829185
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(949)760-9502
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	9497600404
<b>Email:</b>	efiling@knobbe.com
<b>Correspondent Name:</b>	KNOBBE, MARTENS, OLSON & BEAR LLP
<b>Address Line 1:</b>	2040 MAIN STREET
<b>Address Line 2:</b>	14TH FLOOR
<b>Address Line 4:</b>	IRVINE, CALIFORNIA 92614
<b>ATTORNEY DOCKET NUMBER:</b>	TSSRA.051C1/051C2/051C3
<b>NAME OF SUBMITTER:</b>	PAUL STELLMAN
<b>SIGNATURE:</b>	/Paul Stellman/
<b>DATE SIGNED:</b>	12/20/2023
This document serves as an Oath/Declaration (37 CFR 1.63).	
<b>Total Attachments: 4</b>	

source=2023-12-19\_Declaration\_TSSRA.051C2 and 051C3#page1.tif

source=2023-12-19\_Declaration\_TSSRA.051C2 and 051C3#page2.tif

source=2023-12-19\_Declaration\_TSSRA.051C2 and 051C3#page3.tif

source=2023-12-19\_Declaration\_TSSRA.051C2 and 051C3#page4.tif

**PATENT**

**REEL: 065918 FRAME: 0605**

**COMBINED DECLARATION UNDER 37 CFR 1.63 AND ASSIGNMENT**

For good and valuable consideration, the receipt of which is hereby acknowledged, I, an ASSIGNOR named below,

**Rajesh KATKAR** of Milpitas, California, US  
**Liang WANG** of Newark, California, US

hereby sell, assign and transfer to

ASSIGNEE: **Invensas Bonding Technologies, Inc.**, a Delaware corporation having a place of business at: 3025 Orchard Parkway, San Jose, CA 95134,

its successors, assigns and legal representatives, my entire right, title and interest throughout the world, including all rights to claim priority, in and to the invention(s) disclosed in:

- U.S. Patent Application executed on or about the date of this Assignment,
- U.S. Patent Application executed on \_\_\_\_\_, or
- U.S. Patent Application No.: 16/011,525, filed on June 18, 2018
- International Application No.: PCT/\_\_\_\_\_, filed on \_\_\_\_\_

ENTITLED: **BONDED STRUCTURES**

and naming as

INVENTOR(S): **Rajesh KATKAR, Liang WANG**

including without limitation, my entire right, title and interest in and to any and all United States and foreign applications (including any and all provisional, international, regional and foreign national applications) for said invention(s), including non-provisionals, divisions, continuations, continuations-in-part, renewals, substitutes and extensions thereof, and in and to any and all patents of every country or region that may be granted or have been granted for said invention(s), including any reissues and reexaminations thereof.

Assignors hereby grant limited power of attorney to the attorneys/agents associated with Customer No. 79220 & 135980 to update this document, as necessary, with an application number and a filing date for the above-referenced application.

**OATH/DECLARATION**

This Assignment may also serve as an oath or declaration in accord with 37 C.F.R. § 1.63(e) and, as such, as an inventor executing below, I do hereby state that I believe I am the original inventor or an original joint inventor of an invention claimed in any above-identified U.S. Patent Application or International Application designating the United States and do hereby state that such application is and was made or authorized to be made by me. I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

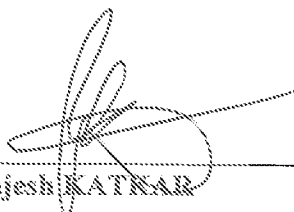
I authorize ASSIGNEE to apply for patents of foreign countries for said invention(s), and to claim all rights of priority without further authorization from me.

I agree to execute any and all papers useful in connection with any and all U.S. and foreign applications (including international, regional, and foreign national applications), and generally to do everything possible to aid ASSIGNEE, its successors, assigns and nominees, at their request and reasonable expense, in obtaining and enforcing patents for said invention(s) in all countries.

I hereby covenant that no assignment, sale, license, agreement, or encumbrance has been or will be made or entered into that would conflict with this Assignment.

I authorize and request the Commissioner of Patents and Trademarks to issue any U.S. Letters Patent that may be granted for said invention(s) to ASSIGNEE, its successors or assigns.

Executed on 8/16/2018  
Date

by   
Rajesh KATKAR

Executed on \_\_\_\_\_  
Date

by \_\_\_\_\_  
Liang WANG

## COMBINED DECLARATION UNDER 37 CFR 1.63 AND ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, an ASSIGNOR named below,

Rajesh KATKAR of Milpitas, California, US  
Liang WANG of Newark, California, US

hereby sell, assign and transfer to

ASSIGNEE: Invensas Bonding Technologies, Inc., a Delaware corporation having a place of business at: 3025 Orchard Parkway, San Jose, CA 95134,

its successors, assigns and legal representatives, my entire right, title and interest throughout the world, including all rights to claim priority, in and to the invention(s) disclosed in:

- U.S. Patent Application executed on or about the date of this Assignment,
- U.S. Patent Application executed on \_\_\_\_\_, or
- U.S. Patent Application No.: 16/011,525, filed on June 18, 2018
- International Application No.: PCT/\_\_\_\_\_, filed on \_\_\_\_\_

ENTITLED: **BONDED STRUCTURES**

and naming as

INVENTOR(S): **Rajesh KATKAR, Liang WANG**

including without limitation, my entire right, title and interest in and to any and all United States and foreign applications (including any and all provisional, international, regional and foreign national applications) for said invention(s), including non-provisionals, divisions, continuations, continuations-in-part, renewals, substitutes and extensions thereof, and in and to any and all patents of every country or region that may be granted or have been granted for said invention(s), including any reissues and reexaminations thereof.

Assignors hereby grant limited power of attorney to the attorneys/agents associated with Customer No. 79220 & 135980 to update this document, as necessary, with an application number and a filing date for the above-referenced application.

### OATH/DECLARATION

This Assignment may also serve as an oath or declaration in accord with 37 C.F.R. § 1.63(e) and, as such, as an inventor executing below, I do hereby state that I believe I am the original inventor or an original joint inventor of an invention claimed in any above-identified U.S. Patent Application or International Application designating the United States and do hereby state that such application is and was made or authorized to be made by me. I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

I authorize ASSIGNEE to apply for patents of foreign countries for said invention(s), and to claim all rights of priority without further authorization from me.

I agree to execute any and all papers useful in connection with any and all U.S. and foreign applications (including international, regional, and foreign national applications), and generally to do everything possible to aid ASSIGNEE, its successors, assigns and nominees, at their request and reasonable expense, in obtaining and enforcing patents for said invention(s) in all countries.

I hereby covenant that no assignment, sale, license, agreement, or encumbrance has been or will be made or entered into that would conflict with this Assignment.

I authorize and request the Commissioner of Patents and Trademarks to issue any U.S. Letters Patent that may be granted for said invention(s) to ASSIGNEE, its successors or assigns.

Executed on \_\_\_\_\_  
Date

by \_\_\_\_\_  
Rajesh KATKAR

Executed on 08/30/2018  
Date

by   
Liang WANG